

#S/B  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Divisional Application of U.S. **09/102,665**

**Hideki MATSUMURA et al.**

Serial No.: **NEW**

Group Art Unit: **1763** (Expected)

Filed: **January 10, 2002**

Examiner: **Lund, J.** (Expected)

For: **METHOD AND APPARATUS FOR DEPOSITING A THIN FILM,  
AND SEMICONDUCTOR DEVICE HAVING A SEMICONDUCTOR-  
INSULATOR JUNCTION**

**PRELIMINARY AMENDMENT**

Commissioner of Patents  
Washington, D.C. 20231

Date: January 10, 2002

Sir:

This is a Preliminary Amendment for the above-captioned Divisional application, concurrently filed herewith. Please amend the above-captioned Divisional application as follows:

**IN THE CLAIMS:**

✓ Please **CANCEL** claims 1-17 without prejudice or disclaimer and **ADD** the following new claim 19:

19. (NEW) Semiconductor device as claimed in claim 18, wherein said semiconductor-insulation junction is one obtained by deposition of said insulator film, which is carried out in said same process chamber after said treatment and utilizes a reaction of a deposition gas supplied with said substrate via said same thermal catalysis body.